

Description

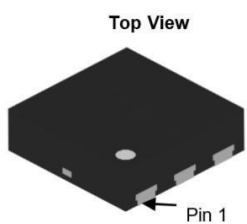
PECJ P-channel Enhancement Mode Power MOSFET

Features

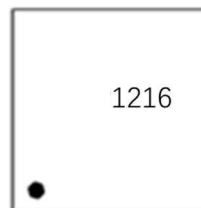
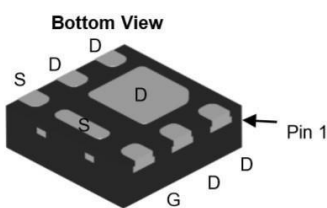
- -12V, -16A
 $R_{DS(ON)} < 18m\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)} < 24m\Omega @ V_{GS} = -2.5V$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

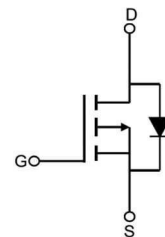
- Load Switch
- PWM Application
- Power management



DFN2X2-6L



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

| Device Marking | Device | OUTLINE | Device Package | Reel Size | Reel (PCS) | Per Carton (PCS) |
|----------------|-----------|---------|----------------|-----------|------------|------------------|
| 1216 | PECJ1216A | TAPING | DFN2X2-6L | 7inch | 4000 | 160000 |

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

| Symbol | Parameter | Max. | Units |
|-----------------|---|---------------------|--------------|
| V_{DSS} | Drain-Source Voltage | -12 | V |
| V_{GSS} | Gate-Source Voltage | ± 12 | V |
| I_D | Continuous Drain Current | $T_C = 25^\circ C$ | -16 |
| | | $T_C = 100^\circ C$ | -10 |
| I_{DM} | Pulsed Drain Current ^{note1} | -64 | A |
| P_D | Power Dissipation | 8 | W |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 15.6 | $^\circ C/W$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ C$ |

Electrical Characteristics (T_J=25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|---|--|------|------|------|-------|
| Off Characteristic | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D = -250μA | -12 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -12V, V _{GS} =0V, | - | - | -1 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±12V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D = -250μA | -0.4 | -0.7 | -1.0 | V |
| R _{DS(on)} | Static Drain-Source on-Resistance <small>note2</small> | V _{GS} = -4.5V, I _D = -8A | - | 14 | 18 | mΩ |
| | | V _{GS} = -2.5V, I _D = -5A | - | 18 | 24 | |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = -6V, V _{GS} =0V, f=1.0MHz | - | 2700 | - | pF |
| C _{oss} | Output Capacitance | | - | 680 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 590 | - | pF |
| Q _g | Total Gate Charge | V _{DS} = -6V, I _D = -8A, V _{GS} = -4.5V | - | 35 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 5 | - | nC |
| Q _{gd} | Gate-Drain("Miller") Charge | | - | 10 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DD} = -6V, I _D = -8A, V _{GS} = -4.5V, R _{GEN} =2.5Ω | - | 11 | - | ns |
| t _r | Turn-on Rise Time | | - | 35 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 30 | - | ns |
| t _f | Turn-off Fall Time | | - | 10 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -16 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -64 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S = -16A | - | -0.8 | -1.2 | V |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure 1: Output Characteristics

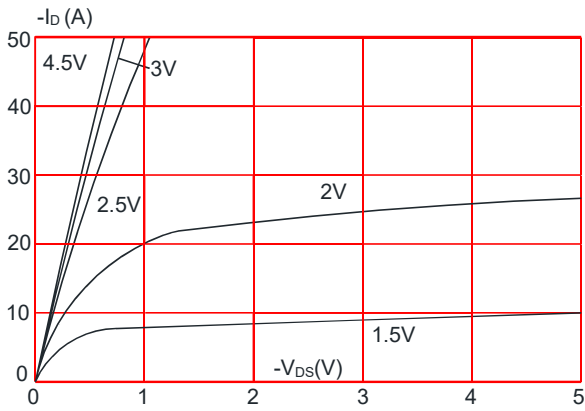


Figure 2: Typical Transfer Characteristics

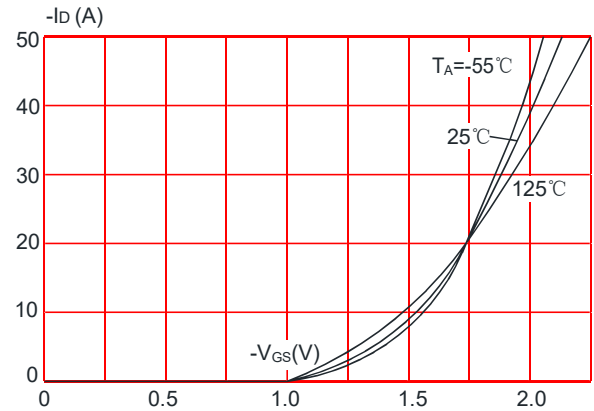


Figure 3: On-resistance vs. Drain Current

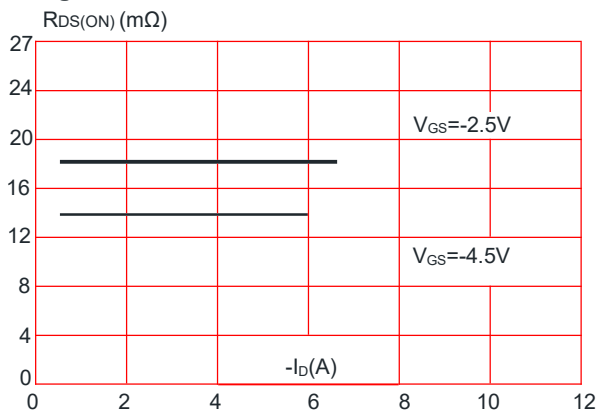


Figure 4: Body Diode Characteristics

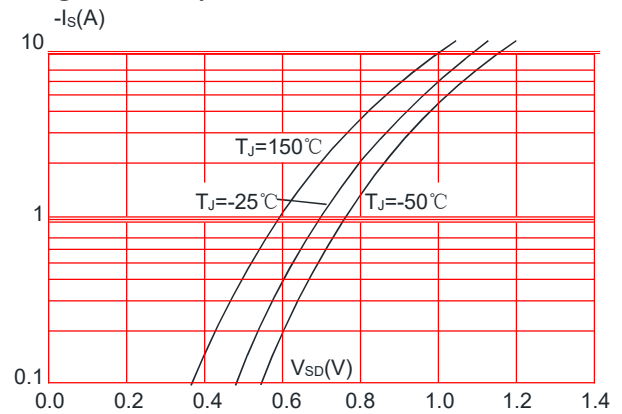


Figure 5: Gate Charge Characteristics

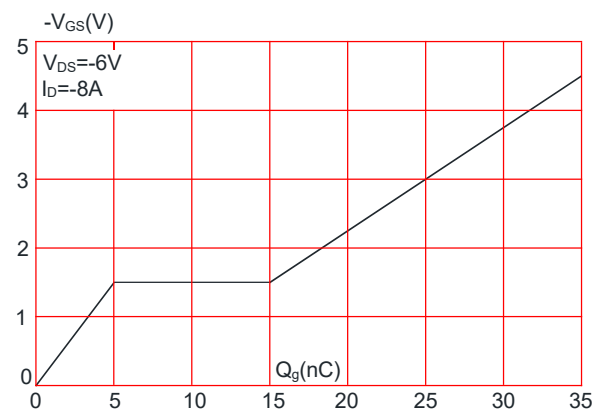


Figure 6: Capacitance Characteristics

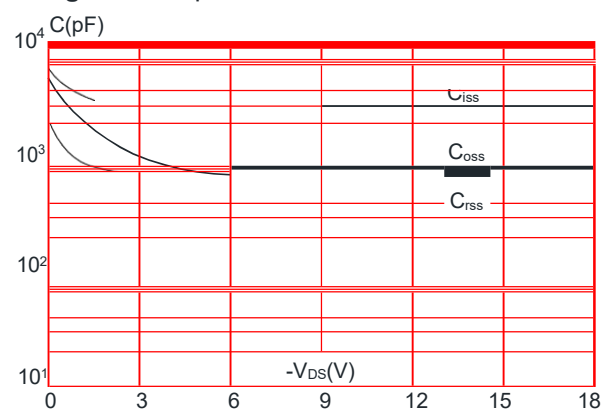


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

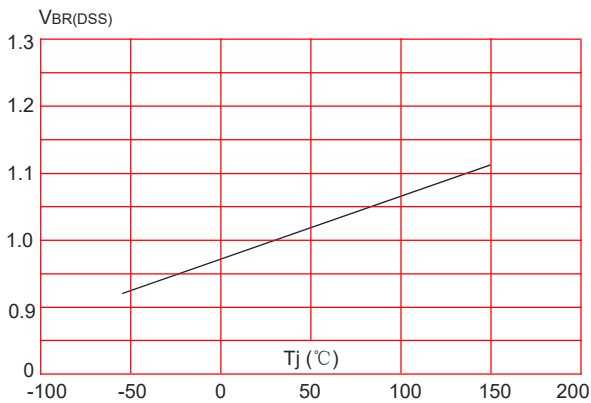


Figure 8: Normalized on Resistance vs. Junction Temperature

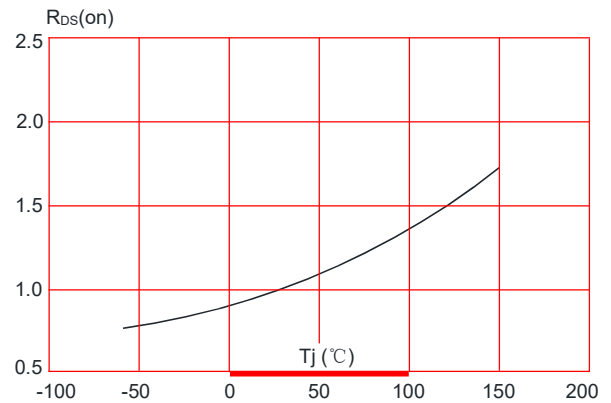


Figure 9: Maximum Safe Operating Area

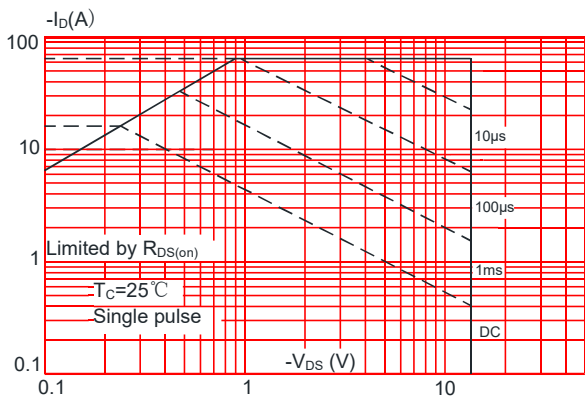


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

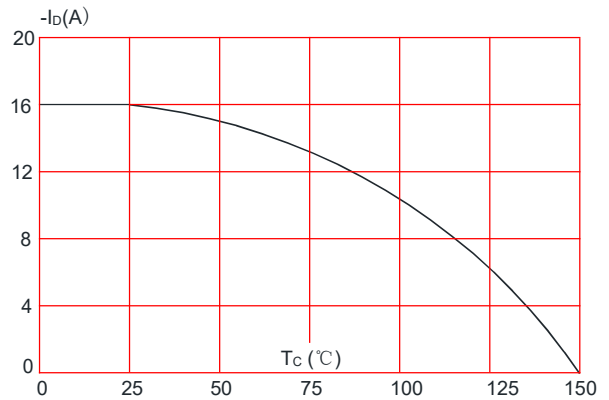
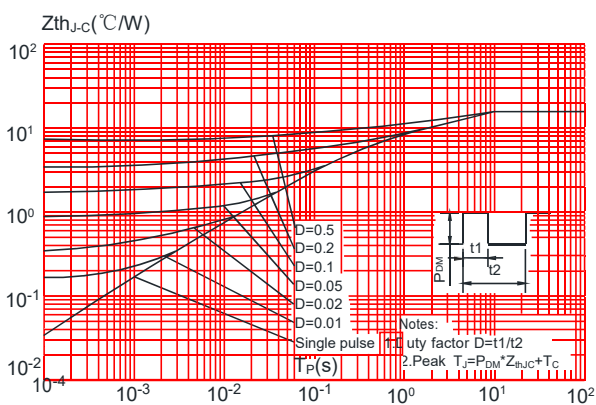
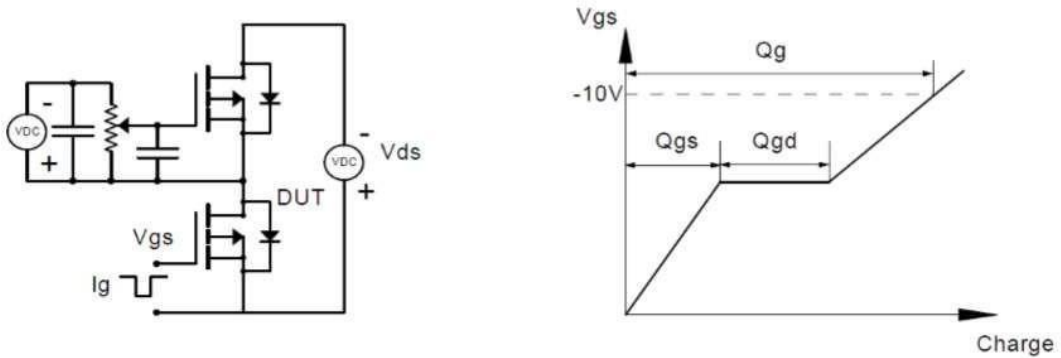


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

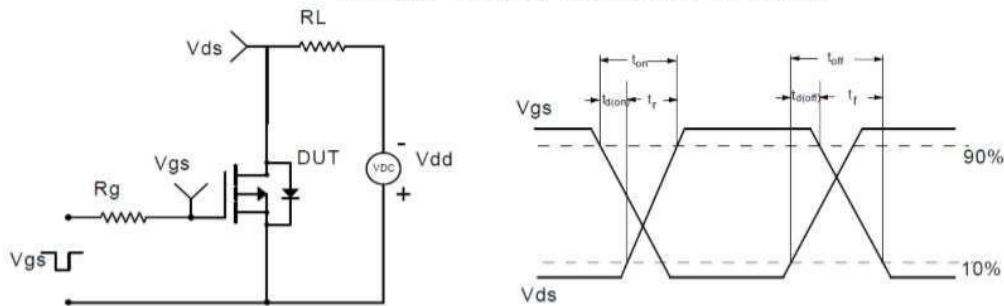


Test Circuit

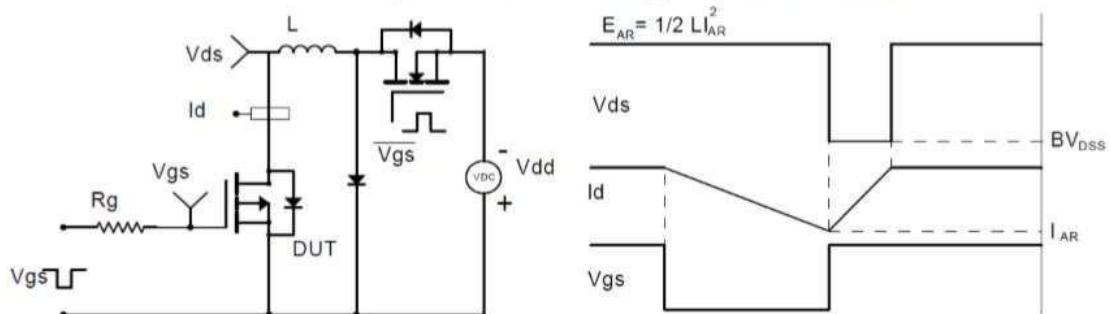
Gate Charge Test Circuit & Waveform



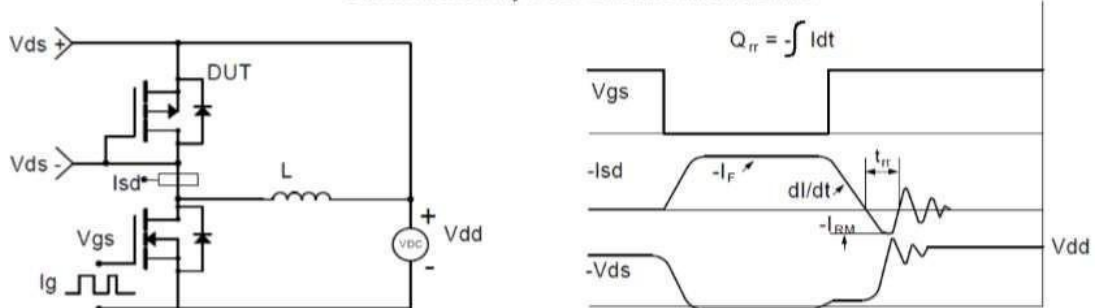
Resistive Switching Test Circuit & Waveforms



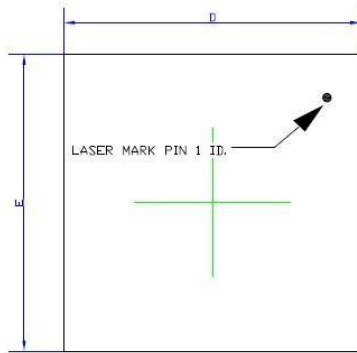
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



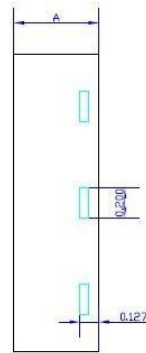
Diode Recovery Test Circuit & Waveforms



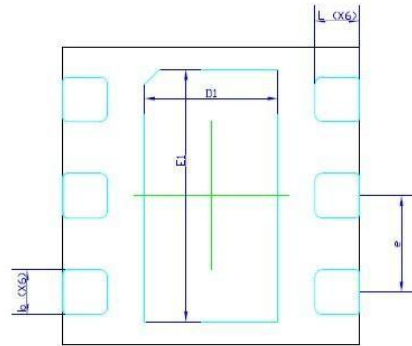
Package Mechanical Data- DFN2X2-6L



TOP VIEW



SIDE VIEW



BOTTOM VIEW

| COMMON DIMENSION (MM) | | | |
|-----------------------|------------|-------|-------|
| PKG | DFN2020-6L | | |
| SYMBOL | MIN. | NOM. | MAX |
| A | 0,527 | 0,552 | 0,577 |
| b | 0,20 | 0,25 | 0,30 |
| D | 1,90 | 2,00 | 2,10 |
| E | 1,90 | 2,00 | 2,10 |
| D1 | 0,80 | 0,90 | 1,00 |
| E1 | 1,60 | 1,70 | 1,80 |
| e | 0,65 REF. | | |
| L | 0,25 | 0,30 | 0,35 |